

S/N Unknown

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Gilroy J. Vandentop et al.

Examiner: Unknown

Serial No.: Unknown

Group Art Unit: Unknown

Filed: Herewith

Docket: 884.540US1

Title: ELECTRONIC PACKAGE HAVING MULTIPLE-ZONE INTERCONNECTS AND  
METHODS OF MANUFACTURE

jc997 U.S. PTO  
10/004002  
11/30/01

**INFORMATION DISCLOSURE STATEMENT**

Assistant Commissioner for Patents  
Washington, D.C. 20231

#2  
10/004002  
2-1808

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants further request that a copy of the 1449 form, initialled by the Examiner to indicate that all listed citations have been considered, be returned with the next official communication.

Please charge any additional fees or credit any overpayment to Account No. 19-0743.

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

GILROY J. VANDENTOP ET AL.

By their Representatives,

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Date

Nov. 30, 2001

By

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Date of Deposit: November 30, 2001

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the US Patent and Trademark Office, Box Patent Application, P.O. Box 2327, Arlington, VA 22202.

Form 1449*	Atty. Docket No.: 884.540US1	Serial No. Unknown
INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Gilroy J. Vandentop et al.	
	Filing Date: Herewith	Group: Unknown

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11/30/01

## U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
	5,321,583	06/14/1994	McMahon, J.F.	361	770	12/02/92
	5,923,083	07/13/1999	Autry, T., et al.	257	688	03/01/97
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## FOREIGN PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes   No
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## OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

**Examiner Initial	
	Ma, L., et al., "Compliant Cantilevered Spring Interconnects for Flip-Chip Packaging", <u>2001 Electronic Components and Technology Conference</u> , 6 pages, (May 2001)
	Ma, L., et al., "Novel Nanospring Interconnects for High-Density Applications", <u>2001 International Symposium on Advanced Packaging Materials</u> , 372-378, (March 2001)
	Naeemi, A., et al., "Sea of Leads: A Disruptive Paradigm for a System-on-a-Chip (SoC)", <u>ISSCC 2001/Session 17/TD: 3D Technologies and Measurement Techniques/17.7</u> , 280-281, (Feb. 2001)
	Reed, H.A., et al., "Compliant Wafer Level Package (CWLP) With Embedded Air-gaps for Sea of Leads (SoL) Interconnections", <u>2001 IEEE</u> , 151-153, (June 2001)

Examiner

Date Considered

\*Substitute Disclosure Statement Form (PTO-1449)

\*\*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.